



3D Packaging and Integration Global Technical Committee

Japan TC Chapter Meeting

Japan Standards Spring 2023 Meetings

Wednesday, March 15, 2023,

Web conference

To be conducted by Official Virtual TC Chapter Meeting

13:30-15:30 Japan Standard Time

AGENDA

1 Welcome / Call to Order

1.1 Introductions

1.2 Meeting Reminders (Membership Requirement, Antitrust and Intellectual Property Reminders, Effective Meeting Guidelines)

1.3 Agenda Review

2 Review of Previous Meeting of 3D Packaging & Integration Japan TC Chapter

3 Liaison Report

3.1 NA TC Chapter

3.2 Taiwan TC Chapter

4 Staff Report

5 Ballot Review

None

6 Task Force & Study Group Reports

6.1 GCS

6.2 3D Packaging & Integration 5 Year Review Task Force

6.3 3DS IC Bonded Layer Inspection Metrology Task Force

6.4 Encapsulation Characteristics for Wafer Level Package and Panel Level Packaging Task Force

6.5 Panel Level Packaging (PLP) Glass Carrier Task Force

6.6 3D Packaging & Integration Steering Group



7 Old Business

7.1 Project Period Review

7.2 5 Year Review Check

7.2.1 SEMI G94-0113 (Reapproved 1118), Specification for Coin-Stack Type Tape Frame Shipping Container for 300 mm Wafer

7.2.2 SEMI G64-1118, Specification for Full-Plated Integrated Circuit Leadframes (Au, Ag, Cu, Ni, Pd/Ni, Pd)

8 New Business

8.1 Proposal of New Activity

9 Action Item Review

9.1 Open Action Items

9.2 New Action Items

10 Next Meeting and Adjournment